

**AMENDMENTS TO THE CLAIMS**

1. (Currently Amended) A contact pin for contacting a terminal of an electronic device to supply the said electronic device with a signal, the contact pin comprising:  
~~provided with~~

a first conductive layer composed of a first conductive material ~~with a high hardness;~~ and

a second conductive layer composed of a second conductive material with a lower hardness than the said first conductive material,

wherein the first conductive layer is formed at the outside from the second conductive layer.

2. (Currently Amended) ~~A contact~~The contact pin as set forth in claim 1, wherein the said first conductive material has a hardness higher than ~~the~~ an oxide film formed on the terminal of the said electronic device; and

the second conductive material has a lower hardness than the oxide film formed on the terminal of the electronic device.

3. (Currently Amended) ~~A contact~~The contact pin as set forth in claim 1, wherein ~~said second conductive material has a lower hardness than the oxide film formed on the terminal of said electronic device~~

the contact pin has a taper portion which tapers toward the front end face of the contact pin, and

the front end face of the contact pin is flat.

4. (Currently Amended) ~~A contact~~The contact pin as set forth in claim 1, wherein the contact pin further comprises a base material at the outside of which the first conductive layer and the second conductive layer are formed,

both the said first conductive layer and the said second conductive layer are exposed at the front end face of the contact pin; and at the wafer side

the base material is arranged inside the contact pin such that the front end of that base material is separated by a predetermined distance from the front end of the contact pin.

5. (Currently Amended) ~~A contact~~The contact pin as set forth in ~~claim 1,~~claim 4, wherein ~~said first conductive layer is formed at the outside from said second conductive layer.~~

the base material has a taper portion which tapers toward the front end of the base material, and

the front end of the base material is a flat surface.

6. (Currently Amended) ~~A contact~~The contact pin as set forth in claim 1, wherein ~~the said first conductive layer is formed so as to be in close contact with the outside of the said second conductive layer.~~

7. (Currently Amended) ~~A contact~~The contact pin as set forth in claim 1, wherein ~~said contact pin is formed finely tapered at its front end~~

the first conductive layer circularly surrounds the second conductive layer in the front end of the contact pin, and

the first and the second conductive layers form the front end face of the contact pin.

8. (Currently Amended) ~~A contact~~The contact pin as set forth in claim 4, ~~claim 1,~~ wherein

~~the pin is further provided with a base material at the outside of which the first conductive layer and second conductive layer are formed,~~

~~said base material being arranged inside said contact pin with the front end of that base material separated by a predetermined distance from the front end of said contact pin~~

the second layer extends between the front end face of the contact pin and the front end of the base material, and the second layer covers the front end of the base material.

9. (Withdrawn – Currently Amended) ~~A contact~~The contact pin as set forth in claim 1, wherein a plurality of at least of said first conductive layer or said second conductive layer is provided.

10. (Currently Amended) A probe card having contact pins of claim 1 electrically connected to a test head of an electronic device test apparatus and a board upon one main surface of which the said contact pins are provided, the said contact pins being brought into contact with terminals of an electronic device to test the said electronic device.

11. (Currently Amended) ~~A probe~~The probe card as set forth in claim 10, wherein the said first conductive material has a hardness higher than the oxide film formed on the terminal of the said electronic device, and  
the second conductive material has a lower hardness than the oxide film formed on the terminal of the electronic device.

12. (Currently Amended) ~~A probe~~The probe card as set forth in claim 10, wherein ~~said second conductive material has a lower hardness than the oxide film formed on the terminal of said electronic device~~  
the contact pin has a taper portion which tapers toward the front end face of the contact pin, and  
the front end face of the contact pin is flat.

13. (Currently Amended) ~~A probe~~The probe card as set forth in claim 10, wherein the contact pin further comprises a base material at the outside of which the first conductive layer and the second conductive layer are formed,  
both the said first conductive layer and the said second conductive layer are exposed at the front end face of the contact pin ~~at the wafer side~~  
the base material is arranged inside the contact pin such that the front end of that base material is separated by a predetermined distance from the front end of the contact pin.

14. (Currently Amended) ~~A probe~~The probe card as set forth in claim 13, claim 10, wherein ~~said first conductive layer is formed at the outside from said second conductive layer~~

the base material has a taper portion which tapers toward the front end of the base material, and

the front end of the base material is a flat surface.

15. (Currently Amended) ~~A probe~~The probe card as set forth in claim 10, wherein the said first conductive layer is formed so as to be in close contact with the outside of the said second conductive layer.

16. (Currently Amended) ~~A probe~~The probe card as set forth in claim 10, wherein ~~said contact pin is formed finely tapered at its front end~~

the first conductive layer circularly surrounds the second conductive layer in the front end of the contact pin, and

the first and the second conductive layers form the front end face of the contact pin.

17. (Currently Amended) ~~A probe~~The probe card as set forth in claim 13, claim 10, wherein

~~the pin is further provided with a base material at the outside of which the first conductive layer and second conductive layer are formed,~~

~~said base material being arranged inside said contact pin with the front end of that base material separated by a predetermined distance from the front end of said contact pin~~

the second layer extends between the front end face of the contact pin and the front end of the base material, and the second layer covers the front end of the base material.

18. (Withdrawn – Currently Amended) ~~A probe~~The probe card as set forth in claim 10, wherein a plurality of at least of said first conductive layer or said second conductive layer is provided.

19. (Original) An electronic device test apparatus having a test head to which a probe card of claim 10 is electrically connected.

20. (Currently Amended) ~~A electronic~~The electronic device test apparatus as set forth in claim 19, wherein

the said first conductive material has a hardness higher than the oxide film formed on the terminal of the said electronic device, and

the second conductive material has a lower hardness than the oxide film formed on the terminal of the electronic device.

21. (Currently Amended) ~~A electronic~~The electronic device test apparatus as set forth in claim 19, wherein

~~said second conductive material has a lower hardness than the oxide film formed on the terminal of said electronic device~~

the contact pin has a taper portion which tapers toward the front end face of the contact pin, and

the front end face of the contact pin is flat.

22. (Currently Amended) ~~A electronic~~The electronic device test apparatus as set forth in claim 19, wherein

the contact pin further comprises a base material at the outside of which the first conductive layer and the second conductive layer are formed,

both the said first conductive layer and the said second conductive layer are exposed at the front end face of the contact pin ~~at the wafer side~~

the base material is arranged inside the contact pin such that the front end of that base material is separated by a predetermined distance from the front end of the contact pin.

23. (Currently Amended) ~~A electronic~~The electronic device test apparatus as set forth in claim ~~22~~ 19, wherein ~~said first conductive layer is formed at the outside from said second conductive layer~~

the base material has a taper portion which tapers toward the front end of the base material, and

the front end of the base material is a flat surface.

24. (Currently Amended) ~~A electronic~~The electronic device test apparatus as set forth in claim 19, wherein the ~~said~~ first conductive layer is formed so as to be in close contact with the outside of the ~~said~~ second conductive layer.

25. (Currently Amended) ~~A electronic~~The electronic device test apparatus as set forth in claim 19, wherein ~~said contact pin is formed finely tapered at its front end~~

the first conductive layer circularly surrounds the second conductive layer in the front end of the contact pin, and

the first and the second conductive layers form the front end face of the contact pin.

26. (Currently Amended) ~~A electronic~~The electronic device test apparatus as set forth in claim 19, wherein

~~the pin is further provided with a base material at the outside of which the first conductive layer and second conductive layer are formed,~~

~~said base material being arranged inside said contact pin with the front end of that base material separated by a predetermined distance from the front end of said contact pin~~

the second layer extends between the front end face of the contact pin and the front end of the base material, and the second layer covers the front end of the base material.

27. (Withdrawn – Currently Amended) ~~A electronic~~ The electronic device test apparatus as set forth in claim 19, wherein a plurality of at least of said first conductive layer or said second conductive layer is provided.